

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24, /26, OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. PLANE LAYERS TO BE 1 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

~~b. IMMERSION SILVER IAG.~~
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.

b. HOLE DIMENSIONS APPLY AFTER PLATING.

c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

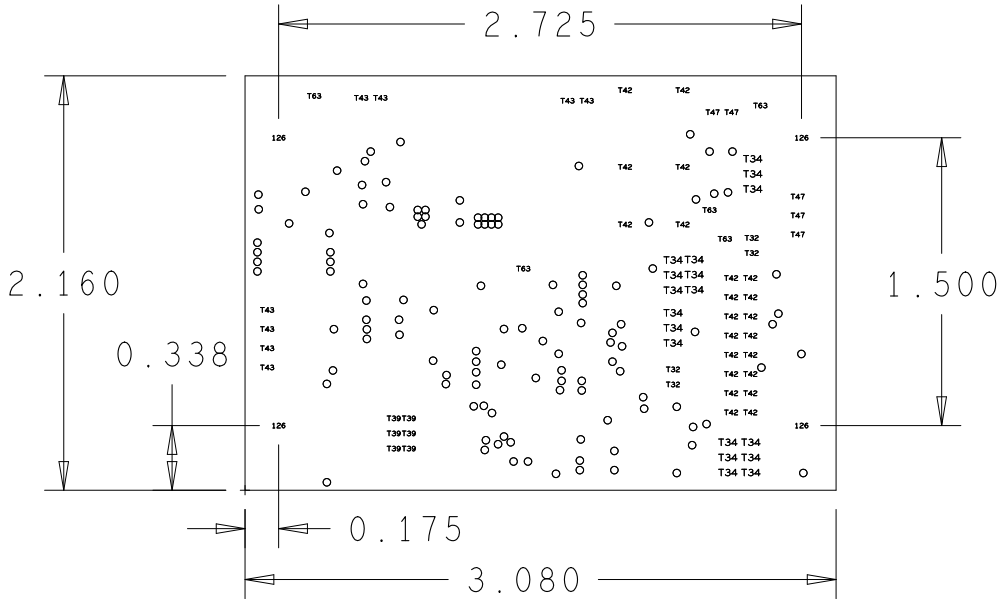
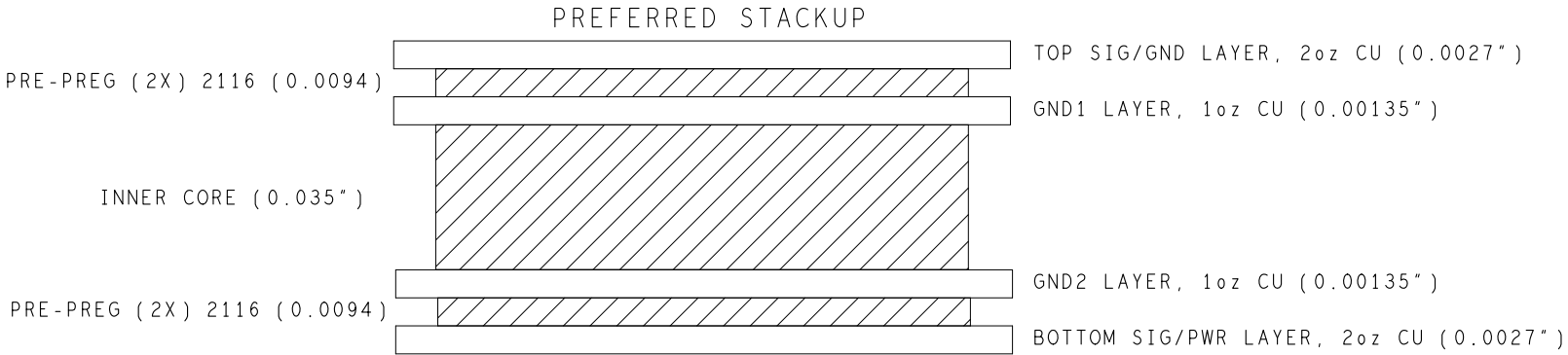
d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
○	10.0	PLATED	121
T32	32.0	PLATED	4
T34	34.0	PLATED	18
T39	39.0	PLATED	6
T42	42.0	PLATED	22
T43	43.0	PLATED	8
T47	47.0	PLATED	5
T63	63.0	PLATED	5
126	126.0	PLATED	4

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	SCPI CONTROL BOARD			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA			
	DESIGNED BY: CHAD KEYC		SIZE B	REVISION C	DWG NO 10020902	
	LAYOUT BY: JOSE ROSAL		SCALE 1 - 1			SHEET 1 - 1